



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|-----------------|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| T | 1.6mm +/-0.20mm |
| B | 0.6mm +/-0.25mm |

Packaging Specifications

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|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 2000 |

General Information

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|--------------------------|--|
| Series | SMD HRA X7R |
| Style | SMD Chip |
| Description | High Reliability Alternative (HRA), X-LEVEL, Flex Termination, SnPb |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov |
| Termination | Flexible Termination With Lead (SnPb) |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 41 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|---|
| Capacitance | 10 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 10% |
| Voltage DC | 6.3 VDC |
| Dielectric Withstanding Voltage | 15.75 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 5% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 50 MOhms |